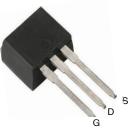


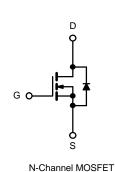
IRF3707L-VB Datasheet

N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^{a, e}	Q _g (Typ)		
30	0.0034 at V _{GS} = 10 V	90	82 nC		
30	0.0070 at V_{GS} = 4.5 V	70	02 110		

TO-262





Top View

FEATURES

- Trench Power MOSFET
- 100 % R_g and UIS Tested
 Compliant to RoHS Directive 2011/65/EU

APPLICATIONS

- OR-ing
- Server
- DC/DC

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	30	V		
Gate-Source Voltage		V _{GS}	± 20	V	
	T _C = 25 °C		90 ^{a, e}		
Continuous Drain Current (T _{.1} = 175 °C)	T _C = 70 °C		65 ^e		
Continuous Drain Current $(T_J = TTS C)$	T _A = 25 °C	I _D	28.8 ^{b, c}	А	
	T _A = 70 °C		27 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	300	1	
Avalanche Current Pulse		I _{AS}	36		
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	104	mJ	
	T _C = 25 °C	1	90 ^{a, e}		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	3.13 ^{b, c}	— A	
	T _C = 25 °C		250 ^a		
Mauianum Davier Dissis ation	T _C = 70 °C	P	175	14/	
Maximum Power Dissipation	T _A = 25 °C	P _D	3.75 ^{b, c}		
	T _A = 70 °C		2.63 ^{b, c}		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS Parameter Symbol Тур. Max. Unit $\mathsf{R}_{\mathsf{thJA}}$ 40 Maximum Junction-to-Ambient^{b, d} $t \leq 10 \text{ sec}$ 32 °C/W Maximum Junction-to-Case Steady State R_{thJC} 0.5 0.6

Notes:

a. Based on T_C = 25 °C. b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 sec.
d. Maximum under steady state conditions is 90 °C/W.
e. Calculated based on maximum junction temperature. Package limitation current is 90 A.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static			I				
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_{D} = 250 \mu A$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 250 4		35		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 7.5			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.5		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zara Cata Valtaga Drain Current	1	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$ $V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			1	μA	
Zero Gate Voltage Drain Current	IDSS				10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	90			А	
		V _{GS} = 10 V, I _D = 20 A		0.0034	0.0034		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 20 \text{ A}$		0.0070		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 28.8 A		160		S	
Dynamic ^b						-	
Input Capacitance	C _{iss}			3500		pF	
Output Capacitance	C _{oss}	V_{DS} = 15 V, V_{GS} = 0 V, f = 1 MHz		1725			
Reverse Transfer Capacitance	C _{rss}			970			
Total Gate Charge	Qg	V_{DS} = 15 V, V_{GS} = 10 V, I_{D} = 28.8 A		171	257	nC	
	-			81.5	123		
Gate-Source Charge	Q _{gs}	V_{DS} = 15 V, V_{GS} = 4.5 V, I_{D} = 28.8 A		34			
Gate-Drain Charge	Q _{gd}			29			
Gate Resistance	Rg	f = 1 MHz		1.4	2.1	Ω	
Turn-On Delay Time	t _{d(on)}			18	27	-	
Rise Time	t _r	V_{DD} = 15 V, R_{L} = 0.625 Ω		11	17		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 24 A, V_{GEN} = 10 V, R_g = 1 Ω		70	105		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			55	83	- ns -	
Rise Time	t _r	V_{DD} = 15 V, R_L = 0.67 Ω		180	270		
Turn-Off Delay Time	t _{d(off)}	$\rm I_D \cong 22.5$ A, $\rm V_{GEN}$ = 4.5 V, $\rm R_g$ = 1 Ω		55	83		
Fall Time	t _f			12	18		
Drain-Source Body Diode Characteristic	cs						
Continuous Source-Drain Diode Current	۱ _S	$T_{C} = 25 \ ^{\circ}C$			90	A	
Pulse Diode Forward Current ^a	I _{SM}				90		
Body Diode Voltage	V _{SD}	I _S = 22 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			52	78	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 20 A, di/dt = 100 A/μs, T _J = 25 °C		70.2	105	nC	
Reverse Recovery Fall Time	t _a			27		ns	
Reverse Recovery Rise Time	t _b			25			

Notes:

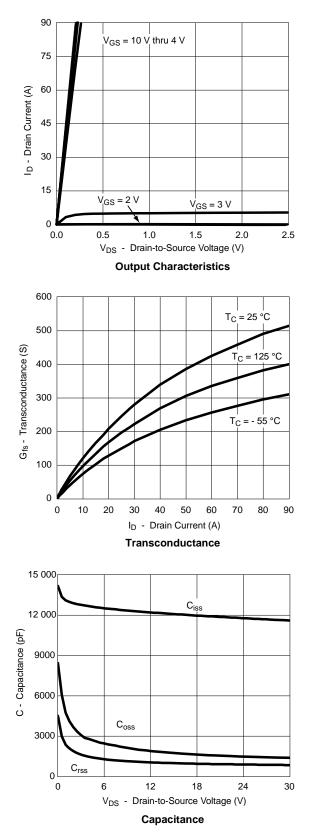
a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle ≤ 2 %.

b. Guaranteed by design, not subject to production testing.

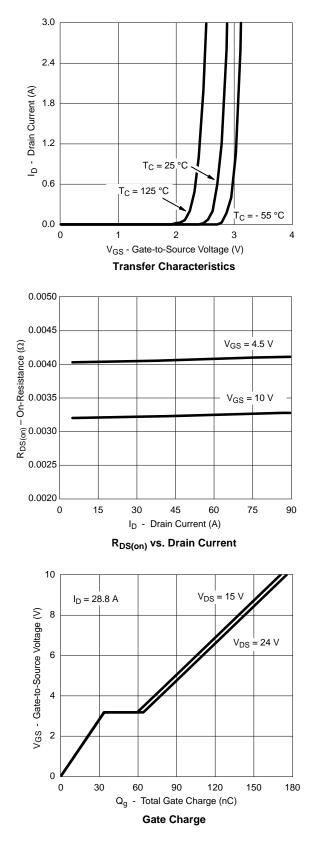
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

emi

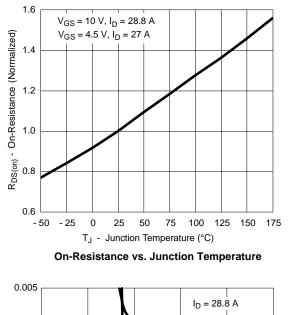




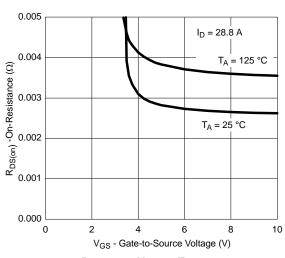
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



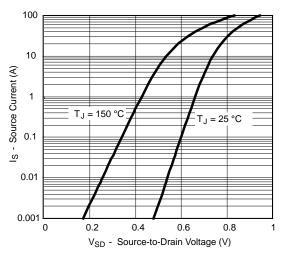




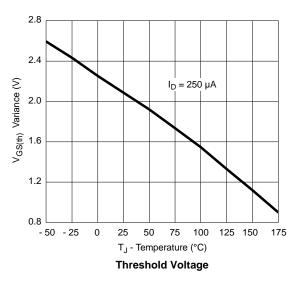
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

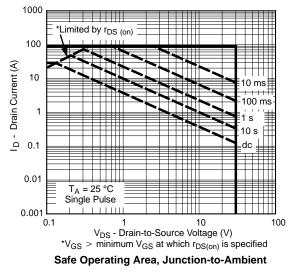


 $R_{DS(on)}$ vs. V_{GS} vs. Temperature

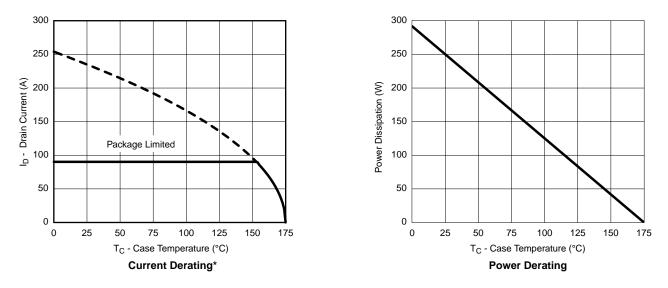


Forward Diode Voltage vs. Temperature









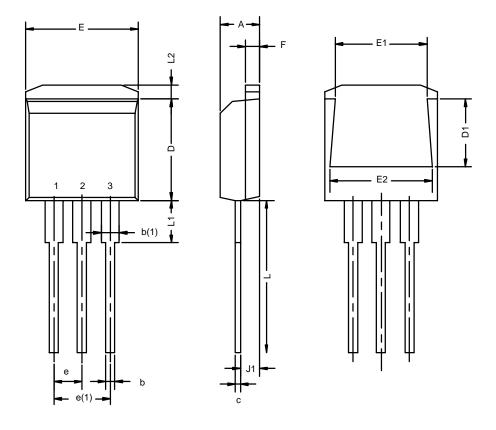
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

*The power dissipation P_D is based on $T_{J(max)} = 175$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





TO-262: 3-LEAD



	MILLIMETERS*		INCHES		
Dim	Min	Max	Min	Max	
Α	4.32	4.70	0.170	0.185	
b	0.64	1.00	0.025	0.039	
b(1)	1.14	1.40	0.045	0.055	
C	0.36	0.50	0.014	0.020	
D	8.64	9.65	0.340	0.380	
D1	5.59	6.10	0.220	0.240	
е	2.41	2.67	0.095	0.105	
e(1)	4.95	5.33	0.195	0.210	
E	10.03	10.41	0.395	0.410	
E1	7.87	8.64	0.310	0.340	
E2	9.02	9.53	0.355	0.375	
F	1.14	1.40	0.045	0.055	
J1	2.41	2.79	0.095	0.110	
L	13.08	14.22	0.515	0.560	
L1	-	3.81	-	0.150	
L2	1.02	1.40	0.040	0.055	
ECN: T-02234—Rev. C, 14-Oct-02 DWG: 5855					

*Use millimeters as the primary measurement



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